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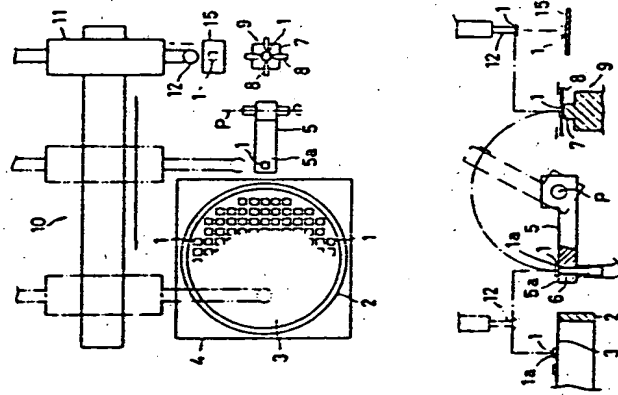
PATENTS ABSTRACTS OF JAPAN

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- (54) DEVICE FOR MOUNTING CHIP
- (11) 1-61027 (A) (43) 8.3.1989 (19) JP
- (21) Appl. No. 62-218892 (22) 31.8.1987
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PURPOSE: To eliminate manual labor in reversing a semiconductor chip and to largely improve working efficiency by reversing the chip upside down by a reversely feeding arm, disposing a bump in a downward attitude, and then placing it on a positioning unit.

CONSTITUTION: A flip-chip 1 disposed on an expanding sheet 10 in an upward attitude of a bump 1a is first fed by a chip feeder 10, and placed on the movable end of a reversely feeding arm 5. The chip 1 attracted to and held at the movable end is placed on a positioning unit 9 by the reversing operation of the arm 5. In this case, the chip 1 is disposed in a downward attitude at its bump 1a. The chip 1 placed on the unit 9 to be positioned is attracted to and held at the feeder 10, fed to a predetermined position on a semiconductor substrate 15, and placed in the downward attitude of the bump 1a. Thus, its working efficiency can be largely improved.



LEGENDE	zu den Bibliographiedaten		(54) Titel der Patentanmeldung	(22) Anmeldetag in Japan
	(11) Nummer der JP-A2 Veröffentlichung		(71) Anmelder	(72) Erfinder
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